Features

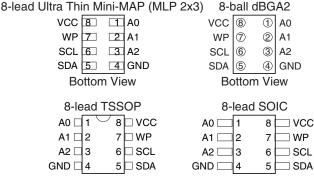
- Low-voltage and Standard-voltage Operation
 - $-1.8 (V_{CC} = 1.8V \text{ to } 5.5V)$
- Internally Organized 128 x 8 (1K)
- Two-wire Serial Interface
- · Schmitt Trigger, Filtered Inputs for Noise Suppression
- Bidirectional Data Transfer Protocol
- 1 MHz (5V), 400 kHz (1.8V, 2.5V, 2.7V) Compatibility
- Write Protect Pin for Hardware Data Protection
- 8-byte Page (1K) Write Modes
- Partial Page Writes Allowed
- Self-timed Write Cycle (5 ms max)
- · High-reliability
 - Endurance: 1 Million Write Cycles
 - Data Retention: 100 Years
- 8-lead PDIP, 8-lead JEDEC SOIC, 8-lead Ultra Thin Mini-MAP (MLP 2x3), 5-lead SOT23, 8-lead TSSOP and 8-ball dBGA2 Packages
- Lead-free/Halogen-free
- Die Sales: Wafer Form and Tape and Reel

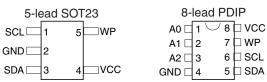
Description

The AT24C01B provides 1024 bits of serial electrically erasable and programmable read-only memory (EEPROM) organized as 128 words of 8 bits each. The device is optimized for use in many industrial and commercial applications where low-power and low-voltage operation are essential. The AT24C01B is available in space-saving 8-lead PDIP, 8-lead JEDEC SOIC, 8-lead Ultra Thin Mini-MAP (MLP 2x3), 5-lead SOT23, 8-lead TSSOP, and 8-ball dBGA2 packages and is accessed via a Two-wire serial interface. In addition, the AT24C01B is available in 1.8V (1.8V to 5.5V) version.

Table 0-1. Pin Configuration

Pin Name	Function
A0 - A2	Address Inputs
SDA	Serial Data
SCL	Serial Clock Input
WP	Write Protect
GND	Ground
VCC	Power Supply







Two-wire Serial EEPROM

1K (128 x 8)

AT24C01B





Absolute Maximum Ratings

Operating Temperature55°C to +125°C
Storage Temperature65°C to +150°C
Voltage on Any Pin with Respect to Ground1.0V to +7.0V
Maximum Operating Voltage 6.25V
DC Output Current 5.0 mA

*NOTICE:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Figure 0-1. Block Diagram

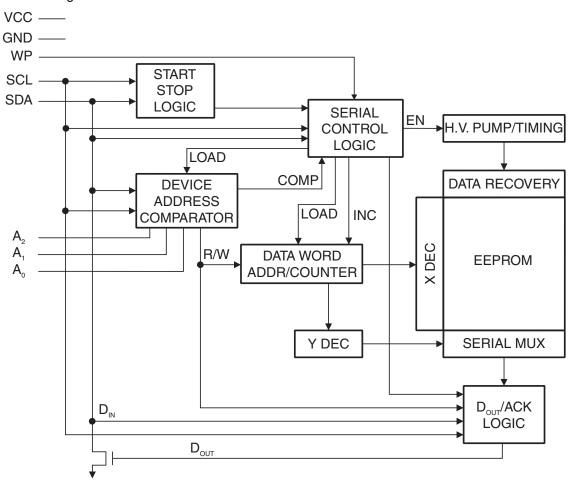




Table 2-1. Pin Capacitance⁽¹⁾

Applicable over recommended operating range from $T_A = 25$ °C, f = 1.0 MHz, $V_{CC} = +1.8$ V

Symbol	Test Condition	Max	Units	Conditions
C _{I/O}	Input/Output Capacitance (SDA)	8	pF	$V_{I/O} = 0V$
C _{IN}	Input Capacitance (A ₀ , A ₁ , A ₂ , SCL)	6	pF	$V_{IN} = 0V$

Note: 1. This parameter is characterized and is not 100% tested.

Table 2-2.DC Characteristics

Applicable over recommended operating range from: $T_{AI} = -40^{\circ}C$ to $+85^{\circ}C$, $V_{CC} = +1.8V$ to +5.5V, $V_{CC} = +1.8V$ to +5.5V (unless otherwise noted)

Symbol	Parameter	Test Condition	Min	Тур	Max	Units
V _{CC1}	Supply Voltage		1.8		5.5	V
V _{CC2}	Supply Voltage		2.5		5.5	V
V _{CC3}	Supply Voltage		2.7		5.5	V
V _{CC4}	Supply Voltage		4.5		5.5	V
I _{cc}	Supply Current V _{CC} = 5.0V	READ at 100 kHz		0.4	1.0	mA
I _{cc}	Supply Current V _{CC} = 5.0V	WRITE at 100 kHz		2.0	3.0	mA
I _{SB1}	Standby Current V _{CC} = 1.8V	$V_{IN} = V_{CC}$ or V_{SS}		0.6	3.0	μΑ
I _{SB2}	Standby Current V _{CC} = 2.5V	$V_{IN} = V_{CC}$ or V_{SS}		1.4	4.0	μΑ
I _{SB3}	Standby Current V _{CC} = 2.7V	$V_{IN} = V_{CC}$ or V_{SS}		1.6	4.0	μA
I _{SB4}	Standby Current V _{CC} = 5.0V	$V_{IN} = V_{CC}$ or V_{SS}		8.0	18.0	μA
I _{LI}	Input Leakage Current	$V_{IN} = V_{CC}$ or V_{SS}		0.10	3.0	μA
I _{LO}	Output Leakage Current	$V_{OUT} = V_{CC}$ or V_{SS}		0.05	3.0	μA
V _{IL}	Input Low Level ⁽¹⁾		-0.6		V _{CC} x 0.3	V
V _{IH}	Input High Level ⁽¹⁾		V _{CC} x 0.7		V _{CC} + 0.5	V
V _{OL2}	Output Low Level V _{CC} = 3.0V	I _{OL} = 2.1 mA			0.4	V
V _{OL1}	Output Low Level V _{CC} = 1.8V	I _{OL} = 0.15 mA			0.2	V

Note: 1. V_{IL} min and V_{IH} max are reference only and are not tested.

 Table 2-3.
 AC Characteristics

Applicable over recommended operating range from $T_{AI} = -40^{\circ}C$ to $+85^{\circ}C$, $V_{CC} = +1.8V$ to +5.5V, CL = 1 TTL Gate and 100 pF (unless otherwise noted)

		1.8, 2.5, 2.7 5.0-volt		volt		
Symbol	Parameter	Min	Max	Min	Max	Units
f _{SCL}	Clock Frequency, SCL		400		1000	kHz
t _{LOW}	Clock Pulse Width Low	1.2		0.4		μs
t _{HIGH}	Clock Pulse Width High	0.6		0.4		μs
t _I	Noise Suppression Time		50		40	ns
t _{AA}	Clock Low to Data Out Valid	0.1	0.9	0.05	0.55	μs
t _{BUF}	Time the bus must be free before a new transmission can start	1.2		0.5		μs
t _{HD.STA}	Start Hold Time	0.6		0.25		μs
t _{SU.STA}	Start Setup Time	0.6		0.25		μs
t _{HD.DAT}	Data In Hold Time	0		0		μs
t _{SU.DAT}	Data In Setup Time	100		100		ns
t _R	Inputs Rise Time ⁽¹⁾		0.3		0.3	μs
t _F	Inputs Fall Time ⁽¹⁾		300		100	ns
t _{SU.STO}	Stop Setup Time	0.6		.25		μs
t _{DH}	Data Out Hold Time	50		50		ns
t _{WR}	Write Cycle Time		5		5	ms
Endurance ⁽¹⁾	5.0V, 25°C, Byte Mode	1 Million		Write Cycles		

Note: 1. This parameter is ensured by characterization only.



AT24C01B Ordering Information

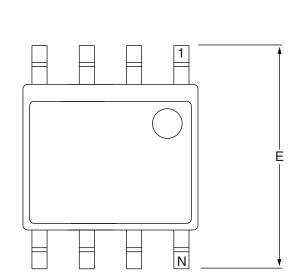
Ordering Code	Package	Voltage Range	Operation Range
AT24C01B-PU (Bulk form only)	8P3	1.8V to 5.5V	
AT24C01BN-SH-B ⁽¹⁾ (NiPdAu Lead Finish)	8S1	1.8V to 5.5V	
AT24C01BN-SH-T ⁽²⁾ (NiPdAu Lead Finish)	8S1	1.8V to 5.5V	
AT24C01B-TH-B ⁽¹⁾ (NiPdAu Lead Finish)	8A2	1.8V to 5.5V	Lead-free/Halogen-free/ Industrial Temperature
AT24C01B-TH-T ⁽²⁾ (NiPdAu Lead Finish)	8A2	1.8V to 5.5V	(-40°C to 85°C)
AT24C01BY6-YH ^{-T(2)} (NiPdAu Lead Finish)	8Y6	1.8V to 5.5V	(10 0 10 00 0)
AT24C01B-TSU ^{-T(2)}	5TS1	1.8V to 5.5V	
AT24C01BU3-UU ^{-T(2)}	8U3-1	1.8V to 5.5V	
AT24C01B-W-11 ⁽³⁾	Die Sale	1.8V to 5.5V	Industrial Temperature
			(–40°C to 85°C)

- Notes: 1. "-B" denotes bulk.
 - 2. "-T" denotes tape and reel. SOIC = 4K per reel. TSSOP, Ultra Thin Mini MAP, SOT 23 and dBGA2 = 5K per reel.
 - 3. Available in tape and reel and wafer form; order as SL788 for inkless wafer form. Please contact Serial Interface Marketing.

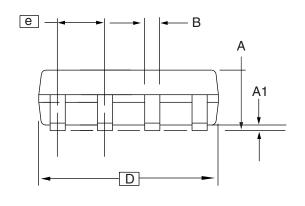
Package Type			
8P3	8-lead, 0.300" Wide, Plastic Dual Inline Package (PDIP)		
8S1	8-lead, 0.150" Wide, Plastic Gull Wing Small Outline (JEDEC SOIC)		
8A2	8-lead, 4.4 mm Body, Plastic Thin Shrink Small Outline Package (TSSOP)		
8Y6	8-lead, 2.0 mm x 3.00 mm Body, 0.50 mm Pitch, Ultra Thin Mini-MAP, Dual No Lead Package (DFN), (MLP 2x3 mm)		
5TS1	5-lead, 2.90 mm x 1.60 mm Body, Plastic Thin Shrink Small Outline Package (SOT23)		
8U3-1	8-ball, die Ball Grid Array Package (dBGA2)		



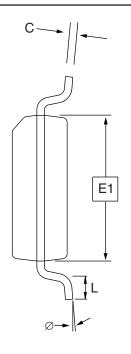
10.2 8S1 - JEDEC SOIC



Top View



Side View



End View

COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
А	1.35	_	1.75	
A1	0.10	-	0.25	
b	0.31	_	0.51	
С	0.17	-	0.25	
D	4.80	_	5.00	
E1	3.81	-	3.99	
Е	5.79	_	6.20	
е		1.27 BSC		
L	0.40	_	1.27	
Ø	0°	_	8°	

Note: These drawings are for general information only. Refer to JEDEC Drawing MS-012, Variation AA for proper dimensions, tolerances, datums, etc.



1150 E. Cheyenne Mtn. Blvd. Colorado Springs, CO 80906 **TITLE 8S1**, 8-lead (0.150" Wide Body), Plastic Gull Wing Small Outline (JEDEC SOIC)

DRAWING NO.	REV.
8S1	В

